

ABSTRACT

An integrated circuit packaging system and method of manufacture thereof including: providing a leadframe having unprocessed leads; depositing an etch mask on a top surface of the unprocessed leads, the unprocessed leads having the etch mask and an unmasked portions of the top surface; connecting an integrated circuit die to the unprocessed leads; encapsulating with a package body the leadframe, the top surface of the unprocessed leads exposed from the package body; forming side-solderable leads including forming a groove in the unprocessed leads, the groove formed under a portion of the etch mask including forming an overhang of the etch mask over the groove; removing the etch mask; and depositing a plating on the side-solderable leads.

(Fig. 4)